



## Product Information Sheet

### EPO-TEK® OG133-7

<b>Date:</b>	December 2017	<b>Recommended Cure:</b> 100mW/cm <sup>2</sup> for 2-3 minutes @ 320-500 nm (depending on thickness)
<b>Rev:</b>	IV	
<b>No. of Components:</b>	Single	
<b>Mix Ratio by Weight:</b>	N/A	
<b>Specific Gravity:</b>	1.11	
<b>Pot Life:</b>	N/A	
<b>Shelf Life- Bulk:</b>	One year at room temperature Keep closed in a dark location when not in use	

#### NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

**Product Description:** A single component, UV curable, flexible epoxy adhesive/encapsulant designed for semiconductor and opto-electronic packaging. Glob top over IC and wire bonds, and low stress bonding of fiber optic components, are common applications. It is a replacement for EPO-TEK® OG133.

**Typical Properties:** Cure condition: varies as required Different batches, conditions & applications yield differing results.  
Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Clear		
* Consistency:	Pourable liquid		
* Viscosity (23°C) @ 100 rpm:	150 - 450	cPs	
Thixotropic Index:	N/A		
* Glass Transition Temp:	≤ 10	°C (Post-Cure Dynamic Scan: 20-200°C; Ramp -40-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
Below Tg:	76	x 10 <sup>-6</sup> in/in°C	
Above Tg:	221	x 10 <sup>-6</sup> in/in°C	
Shore A Hardness:	81		
Lap Shear @ 23°C:	N/A		
Die Shear @ 23°C:	≥ 2.5	Kg	889 psi
Degradation Temp:	361	°C	
Weight Loss:			
@ 200°C:	1.55	%	
@ 250°C:	2.77	%	
@ 300°C:	4.60	%	
Suggested Operating Temperature:	< 250	°C (Intermittent)	
Storage Modulus:	< 1,000	psi	
* Particle Size:	N/A		

OPTICAL PROPERTIES @ 23°C:		
Spectral Transmission:	> 90% @ 440-580	nm
	> 95% @ 600	nm
	> 96% @ 800-1600	nm
Refractive Index (uncured):	1.5060 @589	nm

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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